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Inventor Information for 10/623788

Inventor Name	City	State/Country
FORBES, LEONARD	CORVALLIS	OREGON
GEUSIC, JOSEPH E.	BERKELEY HEIGHTS	NEW JERSEY
AKRAM, SALMAN	BOISE	IDAHO

Appln Info	Contents	Petition Info	Atty/Agent Info	Continuity Data	Foreign Data
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Inventor Name Search Result

Your Search was:

Last Name = GEUSIC

First Name = JOSEPH

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>09643945</u>	6356500	150	08/23/2000	Reduced power dram device and method	GEUSIC, JOSEPH
<u>09734547</u>	6383924	150	12/13/2000	METHOD OF FORMING BURIED CONDUCTOR PATTERNS BY SURFACE TRANSFORMATION OF EMPTY SPACES IN SOLID STATE MATERIALS	GEUSIC, JOSEPH
<u>09940792</u>	Not Issued	93	08/29/2001	BURIED CONDUCTOR PATTERNS BY SURFACE TRANSFORMATION OF EMPTY SPACES IN SOLID STATE MATERIALS	GEUSIC, JOSEPH
<u>09031961</u>	6090636	150	02/26/1998	INTEGRATED CIRCUITS USING OPTICAL WAVEGUIDE INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME	GEUSIC, JOSEPH E.
<u>09504405</u>	6331465	150	02/15/2000	Alternate method and structure for improved floating gate tunneling devices using textured surface	GEUSIC, JOSEPH E
<u>09010729</u>	6025225	150	01/22/1998	CIRCUITS WITH A TRENCH CAPACITOR HAVING MICRO-ROUGHENED SEMICONDUCTOR SURFACES AND METHODS FOR FORMING THE SAME	GEUSIC, JOSEPH E
<u>09257659</u>	6630713	150	02/25/1999	LOW TEMPERATURE SILICON WAFER BOND PROCESS WITH BULK MATERIAL BOND STRENGTH	GEUSIC, JOSEPH E
<u>09394109</u>	6140181	150	09/10/1999	MEMORY USING INSULATOR	GEUSIC, JOSEPH

				TRAPS	E
<u>09484683</u>	<u>6348125</u>	150	01/17/2000	Removal Of Copper Oxides From Integrated Interconnects	GEUSIC, JOSEPH E.
<u>09504496</u>	<u>6294813</u>	150	02/15/2000	Alternate method and structure for improved floating gate tunneling devices	GEUSIC, JOSEPH E.
<u>09513938</u>	<u>6249460</u>	150	02/28/2000	Dynamic flash memory cells with ultrathin tunnel oxides	GEUSIC, JOSEPH E.
<u>09618648</u>	<u>6777715</u>	150	07/18/2000	INTEGRATED CIRCUITS USING OPTICAL WAVEGUIDE INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME	GEUSIC, JOSEPH E.
<u>09641521</u>	<u>6657370</u>	150	08/21/2000	MICROCAVITY DISCHARGE DEVICE FOR EUV LITHOGRAPHY AND OTHER RELATED APPLICATIONS	GEUSIC, JOSEPH E.
<u>09642960</u>	<u>6526191</u>	150	08/21/2000	INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME	GEUSIC, JOSEPH E.
<u>09648884</u>	<u>6602653</u>	150	08/25/2000	CONDUCTIVE MATERIAL PATTERNING METHODS	GEUSIC, JOSEPH E.
<u>09650569</u>	<u>6723577</u>	150	08/30/2000	METHOD OF FORMING AN OPTICAL FIBER INTERCONNECT THROUGH A SEMICONDUCTOR WAFER	GEUSIC, JOSEPH E.
<u>09736247</u>	<u>6579738</u>	150	12/15/2000	METHOD OF ALIGNMENT FOR BURIED STRUCTURES FORMED BY SURFACE TRANSFORMATION OF EMPTY SPACES IN SOLID STATE MATERIALS	GEUSIC, JOSEPH E.
<u>09777816</u>	<u>6451685</u>	150	02/05/2001	METHOD FOR MULTILEVEL COPPER INTERCONNECTS FOR ULTRA LARGE SCALE INTEGRATION	GEUSIC, JOSEPH E.
<u>09800373</u>	<u>6709978</u>	150	03/06/2001	A METHOD FOR FORMING INTEGRATED CIRCUITS USING HIGH ASPECT RATIO VIAS THROUGH A	GEUSIC, JOSEPH E.

				SEMICONDUCTOR WAFER	
<u>09836564</u>	<u>6496370</u>	150	04/17/2001	STRUCTURE AND METHOD FOR AN ELECTRONIC ASSEMBLY	GEUSIC, JOSEPH E.
<u>09855532</u>	Not Issued	91	05/16/2001	METHOD OF FORMING MIRRORS BY SURFACE TRANSFORMATION OF EMPTY SPACES IN SOLID STATE MATERIALS AND STRUCTURES THEREON	GEUSIC, JOSEPH E.
<u>09858304</u>	<u>6545314</u>	150	05/15/2001	MEMORY USING INSULATOR TRAPS	GEUSIC, JOSEPH E.
<u>09861770</u>	<u>6582512</u>	150	05/22/2001	METHOD OF FORMING THREE-DIMENSIONAL PHOTONIC BAND STRUCTURES IN SOLID MATERIALS	GEUSIC, JOSEPH E.
<u>09873701</u>	<u>6476441</u>	150	06/04/2001	METHOD AND STRUCTURE FOR TEXTURED SURFACES IN FLOATING GATE TUNNELING OXIDE DEVICES	GEUSIC, JOSEPH E.
<u>09879453</u>	<u>6351411</u>	150	06/12/2001	Memory using insulator traps	GEUSIC, JOSEPH E.
<u>09882920</u>	<u>6456535</u>	150	06/15/2001	DYNAMIC FLASH MEMORY CELLS WITH ULTRA THIN TUNNEL OXIDES	GEUSIC, JOSEPH E.
<u>09888845</u>	<u>6579803</u>	150	06/25/2001	REMOVAL OF COPPER OXIDES FROM INTEGRATED INTERCONNECTS	GEUSIC, JOSEPH E.
<u>10044097</u>	<u>6593656</u>	150	01/11/2002	METHOD FOR MULTILEVEL COPPER INTERCONNECTS FOR ULTRA LARGE SCALE INTEGRATION	GEUSIC, JOSEPH E.
<u>10052952</u>	<u>6898362</u>	150	01/17/2002	THREE-DIMENSIONAL PHOTONIC CRYSTAL WAVEGUIDE STRUCTURE AND METHOD	GEUSIC, JOSEPH E.
<u>10053003</u>	<u>7018467</u>	150	01/17/2002	THREE-DIMENSIONAL COMPLETE BANDGAP PHOTONIC CRYSTAL FORMED BY CRYSTAL MODIFICATION	GEUSIC, JOSEPH E.
<u>10099044</u>	<u>6829421</u>	150	03/13/2002	HOLLOW CORE PHOTONIC BANDGAP OPTICAL FIBER	GEUSIC, JOSEPH E.
<u>10106915</u>	Not Issued	71	03/25/2002	LOW K INTERCONNECT DIELECTRIC USING SURFACE TRANSFORMATION	GEUSIC, JOSEPH E.

<u>10106916</u>	<u>6943065</u>	150	03/25/2002	SCALABLE HIGH PERFORMANCE ANTIFUSE STRUCTURE AND PROCESS	GEUSIC, JOSEPH E.
<u>10118350</u>	<u>7022604</u>	150	04/09/2002	METHOD OF FORMING SPATIAL REGIONS OF A SECOND MATERIAL IN A FIRST MATERIAL	GEUSIC, JOSEPH E.
<u>10231687</u>	Not Issued	41	08/29/2002	DYNAMIC ELECTRICALLY ALTERABLE PROGRAMMABLE READ ONLY MEMORY DEVICE	GEUSIC, JOSEPH E.
<u>10277043</u>	<u>6949839</u>	150	10/22/2002	Aligned buried structures formed by surface transformation of empty spaces in solid state materials	GEUSIC, JOSEPH E.
<u>10286615</u>	<u>6706597</u>	150	11/01/2002	METHOD FOR TEXTURED SURFACES IN FLOATING GATE TUNNELING OXIDE DEVICES	GEUSIC, JOSEPH E.
<u>10303893</u>	<u>6909113</u>	150	11/26/2002	THREE-DIMENSIONAL PHOTONIC BAND STRUCTURES IN SOLID MATERIALS	GEUSIC, JOSEPH E.
<u>10357844</u>	<u>6812513</u>	150	02/03/2003	METHOD AND STRUCTURE FOR HIGH CAPACITANCE MEMORY CELLS	GEUSIC, JOSEPH E.
<u>10360925</u>	<u>6841408</u>	150	02/10/2003	METHOD OF ALIGNMENT FOR BURIED STRUCTURES FORMED BY SURFACE TRANSFORMATION OF EMPTY SPACES IN SOLID STATE MATERIALS	GEUSIC, JOSEPH E.
<u>10382246</u>	Not Issued	83	03/05/2003	Cellular materials formed using surface transformation	GEUSIC, JOSEPH E.
<u>10404396</u>	Not Issued	93	03/31/2003	REMOVAL OF COPPER OXIDES FROM INTEGRATED INTERCONNECTS	GEUSIC, JOSEPH E.
<u>10419809</u>	<u>6815826</u>	150	04/22/2003	METHOD OF ALIGNMENT FOR BURIED STRUCTURES FORMED BY SURFACE TRANSFORMATION OF EMPTY SPACES IN SOLID STATE MATERIALS	GEUSIC, JOSEPH E.
<u>10435172</u>	<u>6995441</u>	150	05/08/2003	INTEGRATED CIRCUITS USING OPTICAL WAVEGUIDE INTERCONNECTS FORMED THROUGH A	GEUSIC, JOSEPH E.

				SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME	
<u>10461593</u>	Not Issued	71	06/11/2003	DYNAMIC ELECTRICALLY ALTERABLE PROGRAMMABLE READ ONLY MEMORY DEVICE	GEUSIC, JOSEPH E.
<u>10462476</u>	<u>6972257</u>	150	06/16/2003	CONDUCTIVE MATERIAL PATTERNING METHODS	GEUSIC, JOSEPH E.
<u>10464406</u>	Not Issued	160	06/17/2003	Method for multilevel copper interconnects for ultra large scale integration	GEUSIC, JOSEPH E.
<u>10623788</u>	Not Issued	71	07/21/2003	Strained semiconductor by full wafer bonding	GEUSIC, JOSEPH E.
<u>10623794</u>	<u>6929984</u>	150	07/21/2003	GETTERING USING VOIDS FORMED BY SURFACE TRANSFORMATION	GEUSIC, JOSEPH E.
<u>10628243</u>	<u>6894309</u>	150	07/29/2003	SPATIAL REGIONS OF A SECOND MATERIAL IN A FIRST MATERIAL	GEUSIC, JOSEPH E.

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 **PALM INTRANET****Inventor Name Search Result**

Your Search was:

Last Name = AKRAM

First Name = SALMAN

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>08207038</u>	<u>5478779</u>	150	03/07/1994	ELECTRICALLY CONDUCTIVE PROJECTIONS AND SEMICONDUCTOR PROCESSING METHOD OF FORMING SAME	AKRAM, SALMAN
<u>08223642</u>	<u>5419807</u>	150	04/06/1994	METHOD OF PROVIDING ELECTRICAL INTERCONNECT BETWEEN TWO LAYERS WITHIN A SILICON SUBSTRATE, SEMICONDUCTOR APPARATUS, AND METHOD OF FORMING APPARATUS FOR TESTING SEMICONDUCTOR CIRCUITY FOR OPERABILITY	AKRAM, SALMAN
<u>08333262</u>	<u>5444013</u>	150	11/02/1994	METHOD OF FORMING A CAPACITOR	AKRAM, SALMAN
<u>08335262</u>	<u>5495667</u>	150	11/07/1994	METHOD FOR FORMING CONTACT PINS FOR SEMICONDUCTOR DICE AND INTERCONNECTS	AKRAM, SALMAN
<u>08335267</u>	<u>5483741</u>	150	11/07/1994	METHOD FOR FABRICATING A SELF LIMITING SILICON BASED INTERCONNECT FOR TESTING BARE SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08369067</u>	<u>5592736</u>	150	01/05/1995	METHOD FOR FABRICATING AN INTERCONNECT FOR TESTING UNPACKAGED SEMICONDUCTOR DICE HAVING RAISED BOND PADS	AKRAM, SALMAN
<u>08387687</u>	<u>5686317</u>	150	02/13/1995	METHOD FOR FORMING AN	AKRAM, SALMAN

				INTERCONNECT HAVING A PENETRATION LIMITED CONTACT STRUCTURE FOR ESTABLISHING A TEMPORARY ELECTRICAL CONNECTION WITH A SEMICONDUCTOR DIE	
<u>08431452</u>	<u>5578526</u>	150	05/01/1995	METHOD FOR FORMING A MULTI CHIP MODULE (MCM)	AKRAM, SALMAN
<u>08432111</u>	<u>5578934</u>	150	05/01/1995	METHOD AND APPARATUS FOR TESTING UNPACKAGED SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08448758</u>	Not Issued	166	05/24/1995	ELECTRICALLY CONDUCTIVE PROJECTIONS	AKRAM, SALMAN
<u>08452798</u>	<u>5607818</u>	150	05/30/1995	MAKING INTERCONNECTS AND SEMICONDUCTOR STRUCTURES USING ELECTROPHORETIC PHOTORESIST DEPOSITION	AKRAM, SALMAN
<u>08452990</u>	<u>5559444</u>	150	05/30/1995	METHOD AND APPARATUS FOR TESTING UNPACKAGED SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08516973</u>	<u>5658818</u>	150	08/18/1995	SEMICONDUCTOR PROCESSING METHOD EMPLOYING AN ANGLEOL SIDEWALL	AKRAM, SALMAN
<u>08520871</u>	Not Issued	162	08/30/1995	METHOD FOR FORMING A THIN UNIFORM LAYER OF RESIST FOR LITHOGRAPHY	AKRAM, SALMAN
<u>08524018</u>	<u>5716218</u>	150	09/05/1995	PROCESS FOR MANUFACTURING AN INTERCONNECT FOR TESTING A SEMICONDUCTOR DIE	AKRAM, SALMAN
<u>08528126</u>	Not Issued	166	09/14/1995	ELECTRICALLY CONDUCTIVE PROJECTIONS AND SEMICONDUCTOR PROCESSING METHOD OF FORMING SAME	AKRAM, SALMAN
<u>08533373</u>	<u>5946553</u>	150	09/25/1995	A PROCESS FOR MANUFACTURING A SEMICONDUCTOR PACKAGE WITH BI-SUBSTRATE DIE	AKRAM, SALMAN
<u>08563191</u>	<u>5674785</u>	150	11/27/1995	METHOD FOR PRODUCING A SINGLE PIECE PACKAGE FOR SEMICONDUCTOR DIE	AKRAM, SALMAN

<u>08580687</u>	<u>5815000</u>	150	12/29/1995	METHOD FOR TESTING SEMICONDUCTOR DICE WITH CONVENTIONALLY SIZED TEMPORARY PACKAGES	AKRAM, SALMAN
<u>08584628</u>	Not Issued	166	01/11/1996	TEMPORARY SEMICONDUCTOR PACKAGE HAVING DENSE ARRAY EXTERNAL CONTACTS	AKRAM, SALMAN
<u>08587175</u>	<u>5691649</u>	150	01/12/1996	CARRIER HAVING SLIDE CONNECTORS FOR TESTING UNPACKAGED SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08587361</u>	<u>5661334</u>	150	01/16/1996	INTER-METAL DIELECTRIC STRUCTURE WHICH COMBINES FLUORINE-DOPED GLASS AND BARRIER LAYERS	AKRAM, SALMAN
<u>08589924</u>	<u>5741547</u>	150	01/23/1996	METHOD FOR DEPOSITING A FILM OF TITANIUM NITRIDE	AKRAM, SALMAN
<u>08594516</u>	<u>5719425</u>	150	01/31/1996	MULTIPLE IMPLANT LIGHTLY DOPED DRAIN (MILDD) FIELD EFFECT TRANSISTOR	AKRAM, SALMAN
<u>08604007</u>	<u>5742169</u>	150	02/20/1996	APPARATUS FOR TESTING INTERCONNECTS FOR SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08605245</u>	<u>5904546</u>	150	02/12/1996	METHOD AND APPARATUS FOR DICING SEMICONDUCTOR WAFERS	AKRAM, SALMAN
<u>08612059</u>	<u>6072236</u>	150	03/07/1996	MICROMACHINED CHIP SCALE PACKAGE	AKRAM, SALMAN
<u>08612125</u>	<u>5766982</u>	150	03/07/1996	METHOD AND APPARATUS FOR UNDERFILL OF BUMPED OR RAISED DIE	AKRAM, SALMAN
<u>08614178</u>	<u>5682065</u>	150	03/12/1996	HERMETIC CHIP AND METHOD OF MANUFACTURE	AKRAM, SALMAN
<u>08614301</u>	<u>5807762</u>	150	03/12/1996	MULTI-CHIP MODULE SYSTEM AND METHOD OF FABRICATION	AKRAM, SALMAN
<u>08617283</u>	<u>5789271</u>	150	03/18/1996	METHOD FOR FABRICATING MICROBUMP INTERCONNECT FOR BARE SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08621188</u>	Not Issued	164	03/21/1996	ELECTRICALLY CONDUCTIVE PROJECTIONS	AKRAM, SALMAN
<u>08625281</u>	<u>5869974</u>	150	04/01/1996	MICROMACHINED PROBE	AKRAM, SALMAN

				CARD HAVING COMPLIANT CONTACT MEMBERS FOR TESTING SEMICONDUCTOR WAFER	
<u>08628788</u>	Not Issued	161	04/05/1996	METHODS AND APPARATUS FOR FORMING CONTACT AND INTERCONNECT STRUCTURES THROUGH ELECTROLESS COPPER PLATING	AKRAM, SALMAN
<u>08640472</u>	5838161	150	05/01/1996	SEMICONDUCTOR INTERCONNECT HAVING TEST STRUCTURES FOR EVALUATING ELECTRICAL CHARACTERISTICS OF THE INTERCONNECT	AKRAM, SALMAN
<u>08647704</u>	5844419	150	05/14/1996	METHOD FOR TESTING SEMICONDUCTOR PACKAGES USING DECOUPLING CAPACITORS TO REDUCE NOISE	AKRAM, SALMAN
<u>08647749</u>	5808360	150	05/15/1996	MICROBUMP INTERCONNECT FOR BARE SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08651816</u>	5925930	150	05/21/1996	IC CONTENTS WITH PALLADIUM LAYER AND FLEXIBLE CONDUCTIVE EPOXY BUMPS	AKRAM, SALMAN
<u>08653030</u>	5866953	150	05/24/1996	PACKAGED DIE ON PCB WITH HEAT SINK ENCAPSULANT	AKRAM, SALMAN
<u>08657854</u>	5949242	150	05/31/1996	METHOD AND APPARATUS FOR TESTING UNPACKAGED SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08660849</u>	5892281	150	06/10/1996	TANTALUM- ALUMINUM- NITROGEN MATERIAL FOR SEMICONDUCTOR DEVICES	AKRAM, SALMAN
<u>08668765</u>	5723907	150	06/25/1996	LOC SIMM	AKRAM, SALMAN
<u>08673628</u>	Not Issued	166	06/26/1996	STACKED LEADS-OVER-CHIP MULTI-CHIP MODULE	AKRAM, SALMAN
<u>08674473</u>	5929647	150	07/02/1996	METHOD AND APPARATUS FOR TESTING SEMICONDUCTOR DICE	AKRAM, SALMAN
<u>08680790</u>	5849635	150	07/11/1996	SEMICONDUCTOR PROCESSING METHOD OF FORMING AN INSULATING	AKRAM, SALMAN

				DIELECTRIC LAYER AND A CONTACT OPENING THEREIN	
<u>08682141</u>	<u>5736456</u>	150	07/17/1996	METHOD OF FORMING CONDUCTIVE BUMPS ON DIE FOR FLIP CHIP APPLICATIONS	AKRAM, SALMAN
<u>08688060</u>	<u>5739585</u>	150	07/29/1996	SINGLE PIECE PACKAGE FOR SEMICONDUCTOR DIE	AKRAM, SALMAN
<u>08688169</u>	Not Issued	161	09/23/1996	METHOD FOR TESTING UNPACKAGED SEMICONDUCTOR DICE HAVING RAISED BOND PADS	AKRAM, SALMAN
<u>08688368</u>	<u>5789278</u>	150	07/30/1996	METHOD FOR FABRICATING CHIP MODULES	AKRAM, SALMAN
<u>08691759</u>	<u>6005290</u>	150	08/02/1996	MULTI CHIP MODULE HAVING SELF LIMITING CONTACT MEMBERS	AKRAM, SALMAN

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